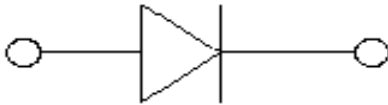


Small Signal Schottky Diode

Features

- V_R 40V/30V/20V
- I_{FAV} 350mA



Mechanical Data

- **Package:** SOD123
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end

	Marking
SD103AW	S4
SD103BW	S5
SD103CW	S6

■Maximum Ratings ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Reverse voltage	V_R	V	$I_R=100\mu\text{A}$	SD103AW	40
				SD103BW	30
				SD103CW	20
Peak forward surge current	I_{FSM}	A	$t_p=8.3\text{ms}$, half sine	1.5	
Average forward current	I_{FAV}	A	$T_c=25^\circ\text{C}$	0.35	
Power dissipation	P_D	mW		400	
Maximum junction temperature	T_J	$^\circ\text{C}$		-55 to +125	
Storage temperature range	T_{stg}	$^\circ\text{C}$		-55 to +150	
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	$^\circ\text{C}/\text{W}$		315	

■Electrical Characteristics ($T_a=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE	
Maximum Forward voltage	V_F	V	$I_F=20\text{mA}$, $T_A=25^\circ\text{C}$	0.37	
	V_F	V	$I_F=200\text{mA}$, $T_A=25^\circ\text{C}$	0.60	
Maximum Reverse current	I_R	μA	SD103AW $V_R=30\text{V}$, $T_A=25^\circ\text{C}$	5.0	
			SD103BW $V_R=20\text{V}$, $T_A=25^\circ\text{C}$		
			SD103CW $V_R=10\text{V}$, $T_A=25^\circ\text{C}$		
Minimum Breakdown voltage	$V_{(BR)}$	V	$I_R=100\mu\text{A}$	SD103AW	40
				SD103BW	30
				SD103CW	20
Typical Junction capacitance	C_J	pF	$V_R=0\text{V}$, $f=1\text{MHz}$	50	

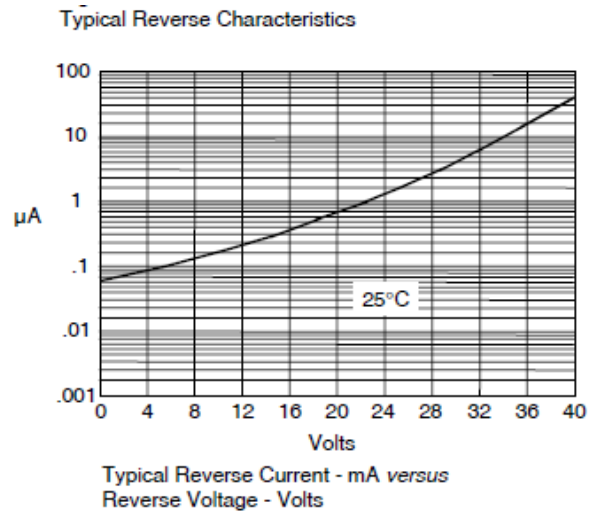
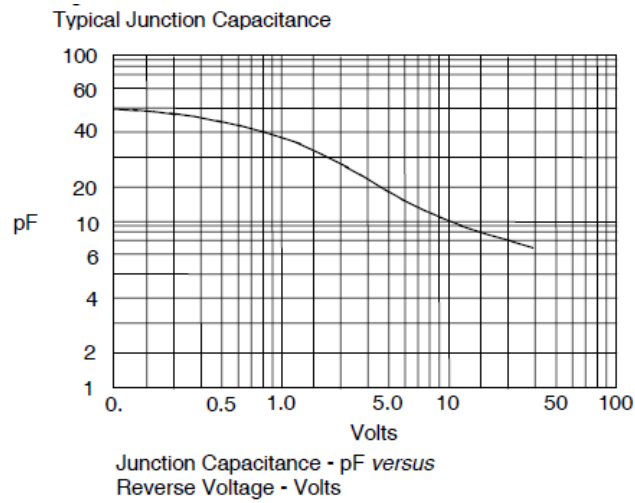
■Ordering Information (Example)

PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SD103AW THRU SD103CW	F2	Approximate 0.011	3000	30000	120000	7" reel

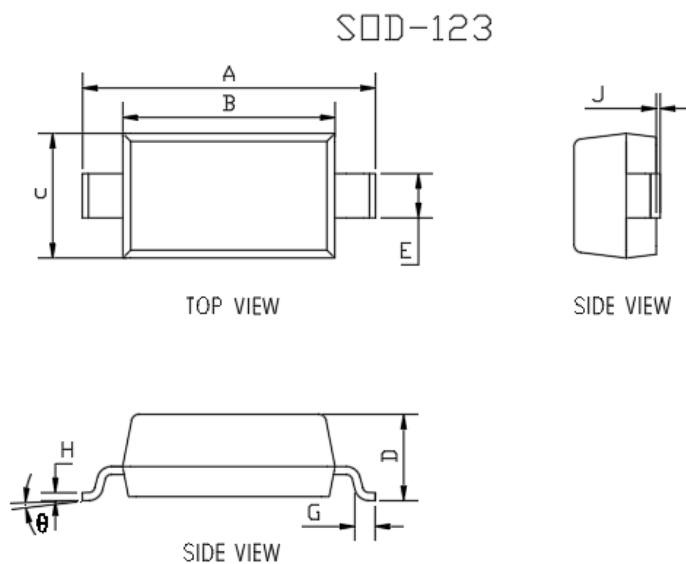


SD103AW THRU SD103CW

■ Characteristics (Typical)

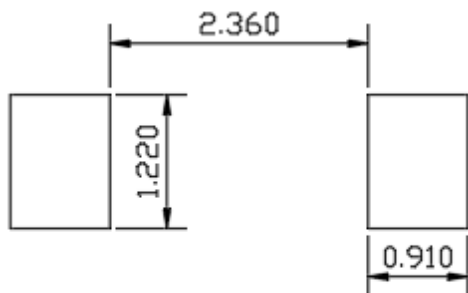


■ Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.140	0.152	3.550	3.850
B	0.100	0.112	2.550	2.850
C	0.055	0.071	1.400	1.800
D	0.037	0.053	0.950	1.350
E	0.020	0.028	0.510	0.710
G	0.006	0.018	0.150	0.450
H	0.003	0.010	0.080	0.250
J	0.000	0.006	0.000	0.150
θ	0	8°	0	8°

■ Soldering Footprint



UNIT : mm

SUGGESTED SOLDER PAD LAYOUT



SD103AW THRU SD103CW

Disclaimer

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